Molecular Structure of the Solid-Liquid Interface and Its Relationship to Electrodeposition 8

Editors:

G. Zangari

R. Alkire

T. Homma

L. A. Kibler

Sponsoring Divisions:

Electrodeposition

Industrial Electrochemistry and Electrochemical Engineering

Published by
The Electrochemical Society
65 South Main Street, Building D
Pennington, NJ 08534-2839, USA
tel 609 737 1902
fax 609 737 2743
www.electrochem.org

ecs transactions™

Vol. 75, No. 35

Copyright 2017 by The Electrochemical Society.
All rights reserved.

This book has been registered with Copyright Clearance Center.
For further information, please contact the Copyright Clearance Center,
Salem, Massachusetts.

Published by:

The Electrochemical Society
65 South Main Street
Pennington, New Jersey 08534-2839, USA

Telephone 609.737.1902
Fax 609.737.2743
e-mail: ecs@electrochem.org
Web: www.electrochem.org

ISSN 1938-6737 (online)
ISSN 1938-5862 (print)
ISSN 2151-2051 (cd-rom)

ISBN 978-1-62332-426-1 (CD-ROM)
ISBN 978-1-60768-784-9 (PDF)

Printed in the United States of America.

***ECS Transactions*, Volume 75, Issue 35**
Molecular Structure of the Solid-Liquid Interface
and Its Relationship to Electrodeposition 8

Table of Contents

Preface *iii*

In-Situ Measurements of Stress during Electrodeposition of Copper Nanofilms: Current Interruption Effects, Migration of Atoms and the Effect of Chloride Ions 1
J. A. Murphy, C. Lenihan, R. P. Lynch, D. N. Buckley

Control of Accumulation of Cu(I) in Copper Sulfate Electroplating Plating Solution 15
T. Koga, C. Hirakawa, Y. Sakata, H. Noma, K. Nonaka, N. Terasaki

Spectroscopic and Electrochemical Analysis of Cu(I) Complex of Copper Sulfate Electroplating Solution and Evaluation of Plated Films 21
T. Koga, C. Hirakawa, Y. Sakata, H. Noma, K. Nonaka, N. Terasaki

Author Index 29